30V P-CHANNEL ENHANCEMENT MODE MOSFET

SUMMARY

 $V(BR)DSS=-30V; RDS(ON)=0.025\Omega; ID=-7.9A$

DESCRIPTION

This new generation of high density MOSFETs from Zetex utilises a unique structure that combines the benefits of low on-resistance with fast switching speed. This makes them ideal for high efficiency, low voltage, power management applications.



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FEATURES

- Low on-resistance
- · Fast switching speed
- · Low threshold
- · Low gate drive
- Low profile SOIC package

APPLICATIONS

- DC DC converters
- Power management functions
- Disconnect switches
- Motor control

ORDERING INFORMATION

DEVICE	REEL SIZE	TAPE WIDTH	QUANTITY PER REEL
ZXM66P03N8TA	7"	12mm	500 units
ZXM66P03N8TC	13"	12mm	2500 units

Top View

DEVICE MARKING

 ZXM 66P03



ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V _{DSS}	-30	V
Gate- Source Voltage	V _{GS}	±20	V
Continuous Drain Current V_{GS} =-10V; T_A =25°C(b) V_{GS} =-10V; T_A =70°C(b) V_{GS} =-10V; T_A =25°C(a)	ID	-7.9 -6.3 -6.25	А
Pulsed Drain Current (c)	I _{DM}	-28	А
Continuous Source Current (Body Diode)(b)	IS	-4.1	А
Pulsed Source Current (Body Diode)(c)	I _{SM}	-28	А
Power Dissipation at T _A =25°C (a) Linear Derating Factor	P _D	1.56 12.5	W mW/°C
Power Dissipation at T _A =25°C (b) Linear Derating Factor	PD	2.5 20	W mW/°C
Operating and Storage Temperature Range	T _j :T _{stg}	-55 to +150	°C

THERMAL RESISTANCE

PARAMETER	SYMBOL	VALUE	UNIT
Junction to Ambient (a)	$R_{ heta JA}$	80	°C/W
Junction to Ambient (b)	$R_{\theta JA}$	50	°C/W

NOTES



⁽a) For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions

⁽b) For a device surface mounted on FR4 PCB measured at t≤10 secs.

⁽c) Repetitive rating 25mm x 25mm FR4 PCB, D = 0.05, pulse width $10\mu s$ - pulse width limited by maximum junction temperature.

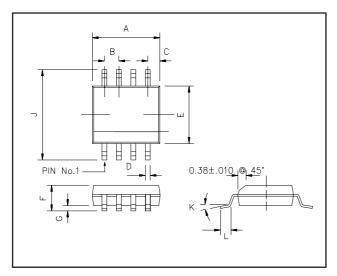
ELECTRICAL CHARACTERISTICS (at T_{amb} = 25°C unless otherwise stated).

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PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS	
STATIC							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	-30			V	I _D =-250μA, V _{GS} =0V	
Zero Gate Voltage Drain Current	I _{DSS}			-1	μА	V _{DS} =-24V, V _{GS} =0V	
Gate-Body Leakage	I _{GSS}			-100	nA	V_{GS} =±20V, V_{DS} =0V	
Gate-Source Threshold Voltage	V _{GS(th)}	-1.0			V	I _D =-250μA, V _{DS} = V _{GS}	
Static Drain-Source On-State Resistance (1)	R _{DS(on)}			0.025 0.035	Ω	V _{GS} =-10V, I _D =-5.6A V _{GS} =-4.5V, I _D =-2.8A	
Forward Transconductance (1)(3)	9fs		14.4		s	V _{DS} =-15V,I _D =-5.6A	
DYNAMIC (3)	•		,				
Input Capacitance	C _{iss}		1979		pF	V _{DS} =-25 V, V _{GS} =0V, f=1MHz	
Output Capacitance	Coss		743		pF		
Reverse Transfer Capacitance	C _{rss}		279		pF		
SWITCHING(2) (3)	•	•					
Turn-On Delay Time	t _{d(on)}		7.6		ns	V _{DD} =-15V, I _D =-5.6A R _G =6.2Ω, V _G S=-10V	
Rise Time	t _r		16.3		ns		
Turn-Off Delay Time	t _{d(off)}		94.6		ns		
Fall Time	tf		39.6		ns		
Gate Charge	Qg		36		nC	V _{DS} =-15V,V _{GS} =-5V I _D =-5.6A	
Total Gate Charge	Qg		62.5		nC	V _{DS} =-15V,V _{GS} =-10V	
Gate-Source Charge	Ogs		4.9		nC		
Gate Drain Charge	Q _{gd}		19.6		nC		
SOURCE-DRAIN DIODE	L	1	1	1	1	1	
Diode Forward Voltage (1)	V _{SD}			-0.95	V	T _j =25°C, I _S =-5.6A, V _{GS} =0V	
Reverse Recovery Time (3)	t _{rr}		35		ns	T _j =25°C, I _F =-5.6A, di/dt= 100A/μs	
Reverse Recovery Charge(3)	O _{rr}		39.9		nC		

- (1) Measured under pulsed conditions. Width=300 $\mu s.$ Duty cycle ${\leq}2\%$.
- $\begin{tabular}{ll} \end{tabular} \begin{tabular}{ll} \textbf{(2) Switching characteristics are independent of operating junction temperature.} \end{tabular}$
- (3) For design aid only, not subject to production testing.



PACKAGE DIMENSIONS



DIM	Millimetres		Inches	
	Min	Max	Min	Max
Α	4.80	4.98	0.189	0.196
В	1.27 BSC		0.05 BSC	
С	0.53 REF		0.02 REF	
D	0.36	0.46	0.014	0.018
E	3.81	3.99	0.15	0.157
F	1.35	1.75	0.05	0.07
G	0.10	0.25	0.004	0.010
J	5.80	6.20	0.23	0.24
K	0°	8°	0°	8°
L	0.41	1.27	0.016	0.050

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